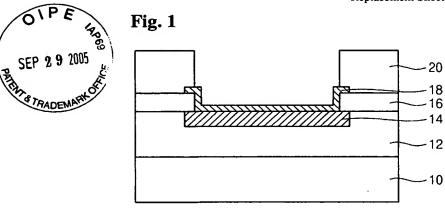
Inventor: Seung Jong YOO
For: "Method for Forming Semiconductor Device Bonding Pads"
Attorney Docket No. 20063/OG03-051 (formerly 20063/10018)
Replacement Sheet



PRIOR ART

Fig. 2

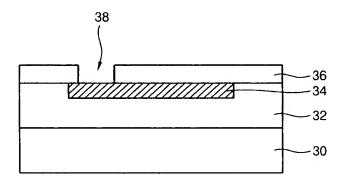


Fig. 3

